

ABSTRACT

An electronic component mounting method comprising:
supplying an unhardened reinforcing resin (3, 15) on a circuit
5 substrate (1); supplying a solder paste (4) on bond areas of
the circuit substrate (1) on which electrodes (5a, 6a) of the
electronic components (5, 6) are to be bonded; placing the
electronic components (5, 6) on the circuit substrate (1); and
heating and then cooling the circuit substrate (1) with the
10 reinforcing resin (3, 15), the solder paste (4), and the
electronic components (5, 6) carried thereon. The mounting
method enables mounting of components with high joint
reliability, while incorporating the conventional surface
mount process steps. The method may also be applied to the
15 mounting of smaller electronic components with narrower pitch
without deteriorating productivity or mounting quality.